

What is claimed is:

1. A prepreg which comprises a substrate and a resin composition containing a resin, an inorganic filler in an amount of 25% by volume or more based on the total volume of a solid component of the resin composition and a silicone polymer, which resin composition being impregnated into the substrate.
2. The prepreg according to claim 1, wherein the inorganic filler has previously been subjected to surface treatment by a silicone polymer.
3. The prepreg according to claim 2, wherein the resin composition further contains a coupling agent.
4. A metal-clad laminated board which comprises at least one metal foil being laminated on both surfaces or one surface of the prepreg according to claim 1, or a laminated board thereof under heating and pressure.
5. The prepreg according to claim 2, wherein the resin composition is a resin composition in which a resin is formulated in a solution containing a silicone polymer into which the inorganic filler is dispersed.
6. The prepreg according to claim 2, wherein the resin composition is a resin composition in which a resin is formulated in a solution containing a silicone polymer into which the inorganic filler is dispersed, and a coupling agent.
7. The prepreg according to claim 2, wherein the silicone polymer is a three-dimensionally cross-linked polymer.
8. The prepreg according to claim 7, wherein the silicone polymer is a silicone polymer containing a least one of a tri-functional siloxane unit represented by the formula: $R^3SiO_{3/2}$ (wherein R^1 represents a same or different organic group) or a tetra-functional siloxane unit represented by the formula: $SiO_{4/2}$ in the molecule.
9. The prepreg according to claim 8, wherein the silicone polymer is a silicone polymer containing 15 to 100 mol % of at least one of a tetra-functional siloxane unit and a tri-functional siloxane unit in the molecule based on the total siloxane units, and 0 to 85 mol % of a bi-functional siloxane unit.
10. The prepreg according to claim 9, wherein the silicone polymer is a silicone polymer containing 15 to 100 mol % of a tetra-functional siloxane unit, 0 to 85 mol % of a tri-functional siloxane unit, and 0 to 85 mol % of a bi-functional siloxane unit in the molecule based on the total siloxane units.
11. A metal-clad-laminated board which comprises at least one metal foil being laminated on both surfaces or one surface of the prepreg according to claim 2, or a laminated board thereof under heating and pressure.
12. The metal-clad-laminated board according to claim 11, wherein a surface hardness of the metal-clad-laminated board at a portion containing no metal foil is 30 or more at 200° C. in terms of a Barcol hardness.
13. A printed wiring board which comprises the metal-clad-laminated board according to claim 11 obtained by subjecting the board to circuit processing.

14. A printed wiring board which comprises the metal-clad-laminated board according to claim 12 obtained by subjecting the board to circuit processing.
15. The prepreg according to claim 1, wherein the resin composition further contains a coupling agent.
16. The prepreg according to claim 1, wherein the inorganic filler has previously been subjected to surface treatment by a silicone polymer and a coupling agent.
17. The prepreg according to claim 1, wherein the resin composition is a resin composition in which a resin is formulated in a solution containing a silicone polymer into which the inorganic filler is dispersed.
18. The prepreg according to claim 1, wherein the resin composition is a resin composition in which a resin is formulated in a solution containing a silicone polymer into which the inorganic filler is dispersed, and a coupling agent.
19. The prepreg according to claim 1, wherein the silicone polymer is a three-dimensionally cross-linked polymer.
20. The prepreg according to claim 19, wherein the silicone polymer is a silicone polymer containing a least one of a tri-functional siloxane unit represented by the formula: $R^3SiO_{3/2}$ (wherein R^1 represents a same or different organic group) or a tetra-functional siloxane unit represented by the formula: $SiO_{4/2}$ in the molecule.
21. The prepreg according to claim 20, wherein the silicone polymer is a silicone polymer containing 15 to 100 mol % of at least one of a tetra-functional siloxane unit and a tri-functional siloxane unit in the molecule based on the total siloxane units, and 0 to 85 mol % of a bi-functional siloxane unit.
22. The prepreg according to claim 21, wherein the silicone polymer is a silicone polymer containing 15 to 100 mol % of a tetra-functional siloxane unit, 0 to 85 mol % of a tri-functional siloxane unit, and 0 to 85 mol % of a bi-functional siloxane unit in the molecule based on the total siloxane units.
23. The metal-clad-laminated board according to claim 4, wherein a surface hardness of the metal-clad-laminated board at a portion containing no metal foil is 30 or more at 200° C. in terms of a Barcol hardness.
24. A printed wiring board which comprises the metal-clad-laminated board according to claim 4 obtained by subjecting the board to circuit processing.
25. A printed wiring board which comprises the metal-clad-laminated board according to claim 23 obtained by subjecting the board to circuit processing.
26. The prepreg according to claim 1, which includes said inorganic filler in an amount of 25%-65% by volume based on the total volume of the solid component of the resin composition.
27. A metal-clad-laminated board which comprises at least one metal foil being laminated on both surfaces or one surface of the prepreg according to claim 26, or a laminated board thereof under heating and pressure.
28. A printed wiring board which comprises the metal-clad-laminated board according to claim 27 obtained by subjecting the board to circuit processing.